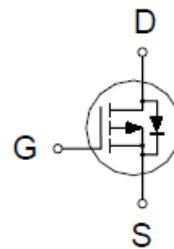
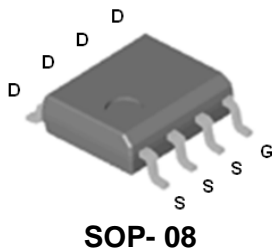


# PV563BA

## P-Channel Enhancement Mode MOSFET

### PRODUCT SUMMARY

$V_{(BR)DSS}$	$R_{DS(ON)}$	$I_D$
-40V	15m $\Omega$ @ $V_{GS} = -10V$	-9.5A



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNITS
Drain-Source Voltage		$V_{DS}$	-40	V
Gate-Source Voltage		$V_{GS}$	$\pm 25$	
Continuous Drain Current	$T_A = 25\text{ }^\circ\text{C}$	$I_D$	-9.5	A
	$T_A = 70\text{ }^\circ\text{C}$		-7.6	
Pulsed Drain Current <sup>1</sup>		$I_{DM}$	-40	
Avalanche Current		$I_{AS}$	-32	
Avalanche Energy	L=0.1mH	$E_{AS}$	53	mJ
Power Dissipation <sup>3</sup>	$T_A = 25\text{ }^\circ\text{C}$	$P_D$	3	W
	$T_A = 70\text{ }^\circ\text{C}$		2	
Junction & Storage Temperature Range		$T_J, T_{STG}$	-55 to 150	$^\circ\text{C}$

### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE		SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Ambient <sup>2</sup>	$t \leq 10s$	$R_{\theta JA}$		40	$^\circ\text{C} / \text{W}$
Junction-to-Ambient <sup>2</sup>	Steady-State	$R_{\theta JA}$		75	
Junction-to-Case	Steady-State	$R_{\theta JC}$		24	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz. Copper in a still air environment with  $T_A=25^\circ\text{C}$ .

<sup>3</sup>The Power dissipation is based on  $R_{\theta JA} t \leq 10s$  value.

# PV563BA

## P-Channel Enhancement Mode MOSFET

### ELECTRICAL CHARACTERISTICS (T<sub>J</sub> = 25 °C, Unless Otherwise Noted)

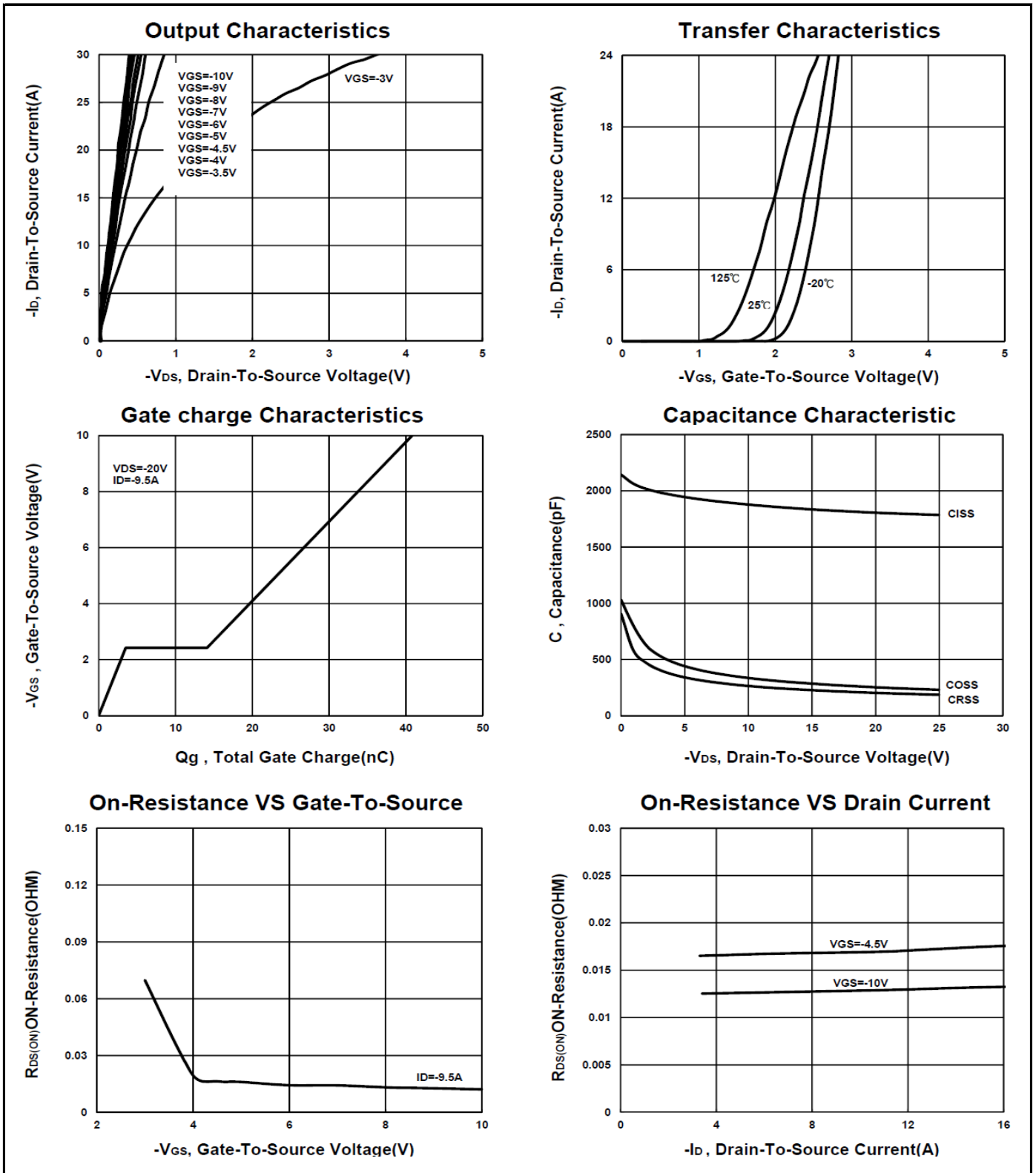
PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNITS
			MIN	TYP	MAX	
<b>STATIC</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-40			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.3	-1.5	-3	
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±25V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -32V, V <sub>GS</sub> = 0V			-1	μA
		V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 55 °C			-10	
Drain-Source On-State Resistance <sup>1</sup>	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -9.5A		17	29	mΩ
		V <sub>GS</sub> = -10V, I <sub>D</sub> = -9.5A		13	15	
Forward Transconductance <sup>1</sup>	g <sub>fs</sub>	V <sub>DS</sub> = -5V, I <sub>D</sub> = -9.5A		20		S
<b>DYNAMIC</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = -20V, f = 1MHz		1883		pF
Output Capacitance	C <sub>oss</sub>			255		
Reverse Transfer Capacitance	C <sub>rss</sub>			213		
Gate Resistance	R <sub>g</sub>	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V, f = 1MHz		4		Ω
Total Gate Charge <sup>2</sup>	Q <sub>g</sub>	V <sub>DS</sub> = -20V I <sub>D</sub> = -9.5A, V <sub>GS</sub> = -10V		41.2		nC
Gate-Source Charge <sup>2</sup>	Q <sub>gs</sub>			4.2		
Gate-Drain Charge <sup>2</sup>	Q <sub>gd</sub>			14		
Turn-On Delay Time <sup>2</sup>	t <sub>d(on)</sub>	V <sub>DD</sub> = -20V, I <sub>D</sub> ≅ -9.5A, V <sub>GS</sub> = -10V, R <sub>GEN</sub> = 3Ω		9.4		nS
Rise Time <sup>2</sup>	t <sub>r</sub>			20		
Turn-Off Delay Time <sup>2</sup>	t <sub>d(off)</sub>			55		
Fall Time <sup>2</sup>	t <sub>f</sub>			30		
<b>SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS (T<sub>J</sub> = 25 °C)</b>						
Continuous Current	I <sub>S</sub>				-2.3	A
Forward Voltage <sup>1</sup>	V <sub>SD</sub>	I <sub>F</sub> = -9.5A, V <sub>GS</sub> = 0V			-1.3	V
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = -9.5A, dI/dt = 100A / μS		20		nS
Reverse Recovery Charge	Q <sub>rr</sub>				6	

<sup>1</sup>Pulse test : Pulse Width ≤ 300 μsec, Duty Cycle ≤ 2%.

<sup>2</sup>Independent of operating temperature.

# PV563BA

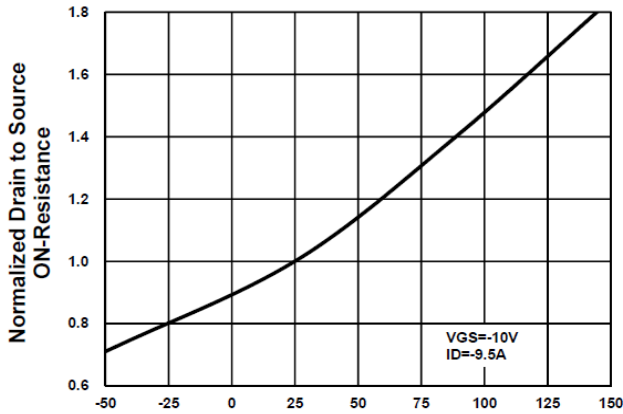
## P-Channel Enhancement Mode MOSFET



# PV563BA

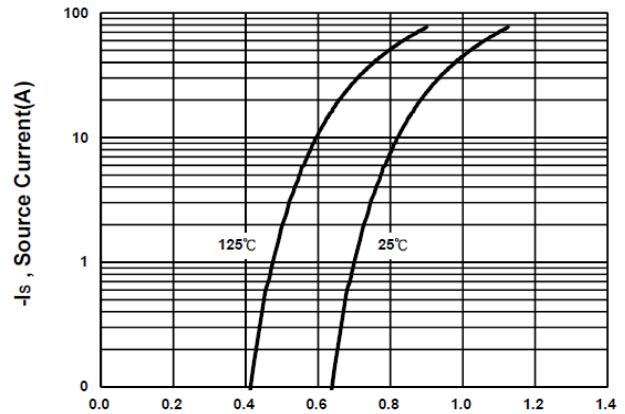
## P-Channel Enhancement Mode MOSFET

**On-Resistance VS Temperature**



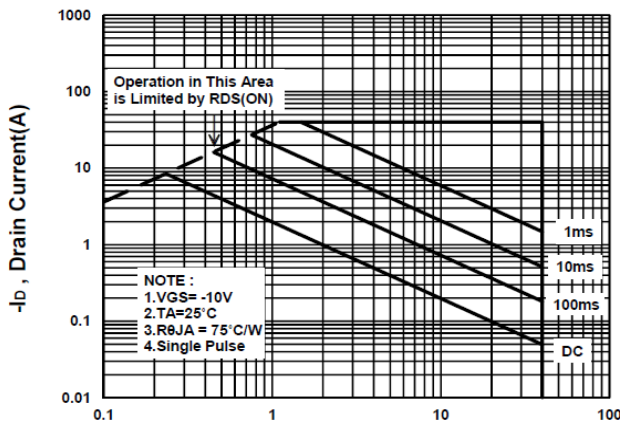
$T_j$ , Junction Temperature(°C)

**Source-Drain Diode Forward Voltage**



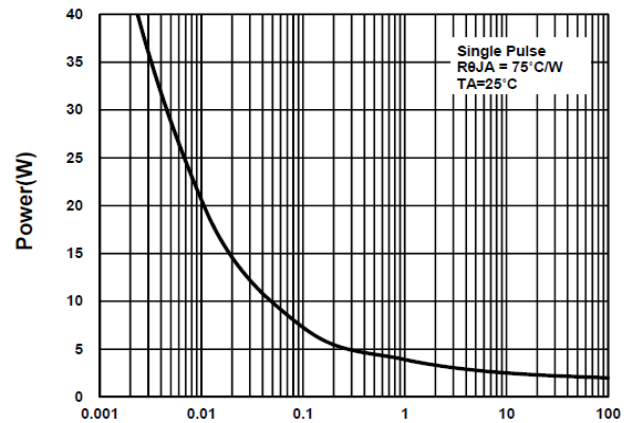
$-V_{SD}$ , Source-To-Drain Voltage(V)

**Safe Operating Area**



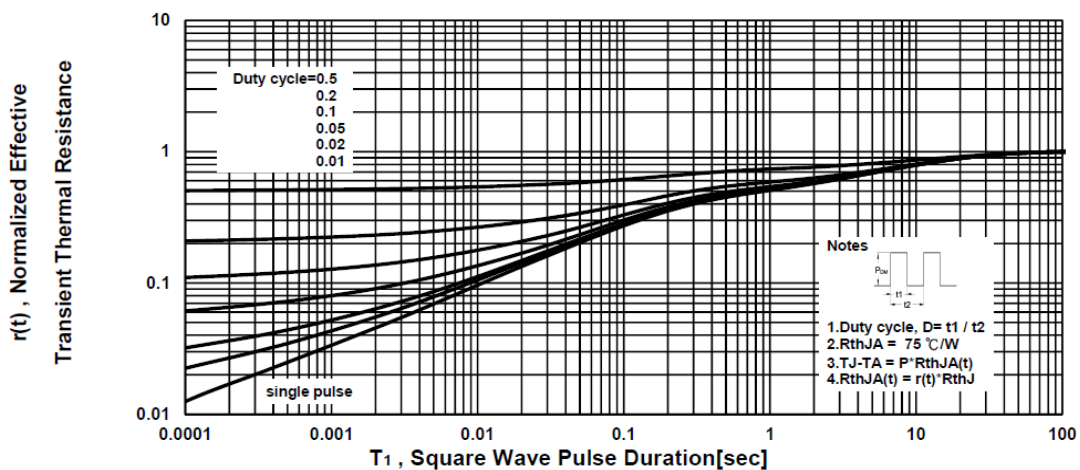
$-V_{DS}$ , Drain-To-Source Voltage(V)

**Single Pulse Maximum Power Dissipation**



Single Pulse Time(s)

**Transient Thermal Response Curve**

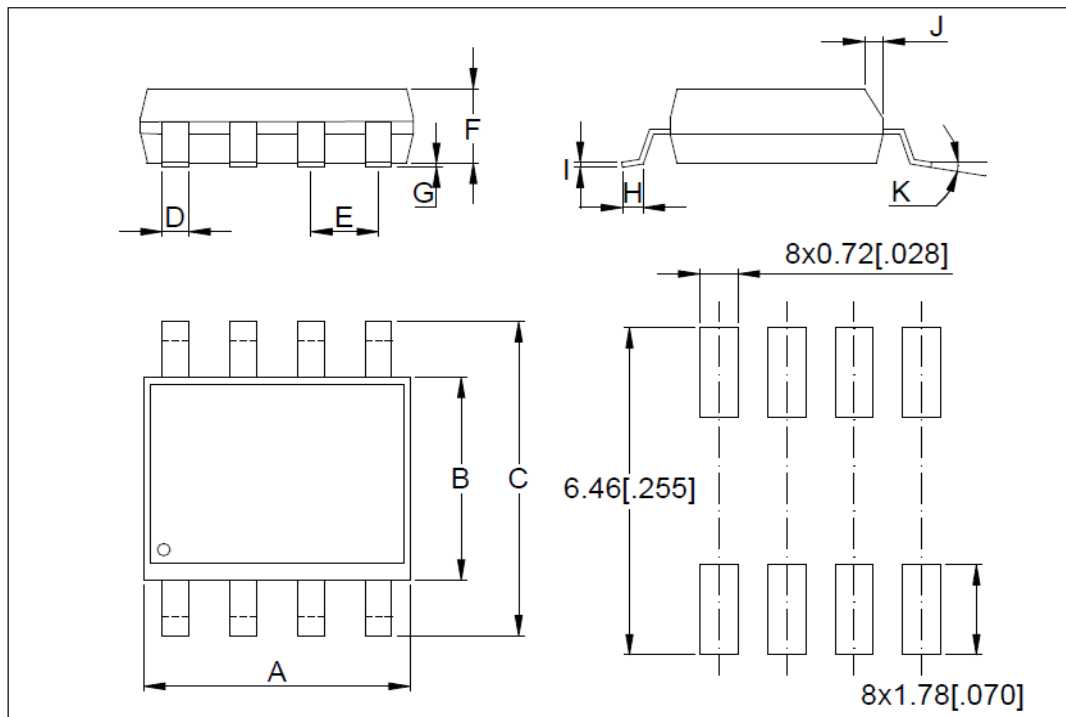


**PV563BA**  
**P-Channel Enhancement Mode MOSFET**

**Package Dimension**

**SOP-8 MECHANICAL DATA**

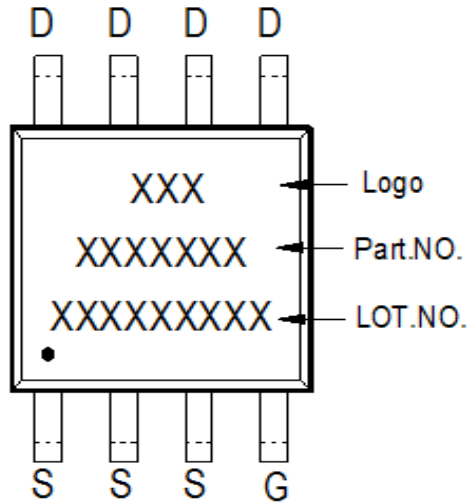
Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.8	4.9	5.0	H	0.4	0.6	0.93
B	3.8	3.9	4.0	I	0.19	0.21	0.25
C	5.79	6.0	6.2	J	0.25	0.375	0.5
D	0.33	0.4	0.51	K	0°	3°	18°
E	1.25	1.27	1.29				
F	1.1	1.3	1.65				
G	0.05	0.15	0.25				



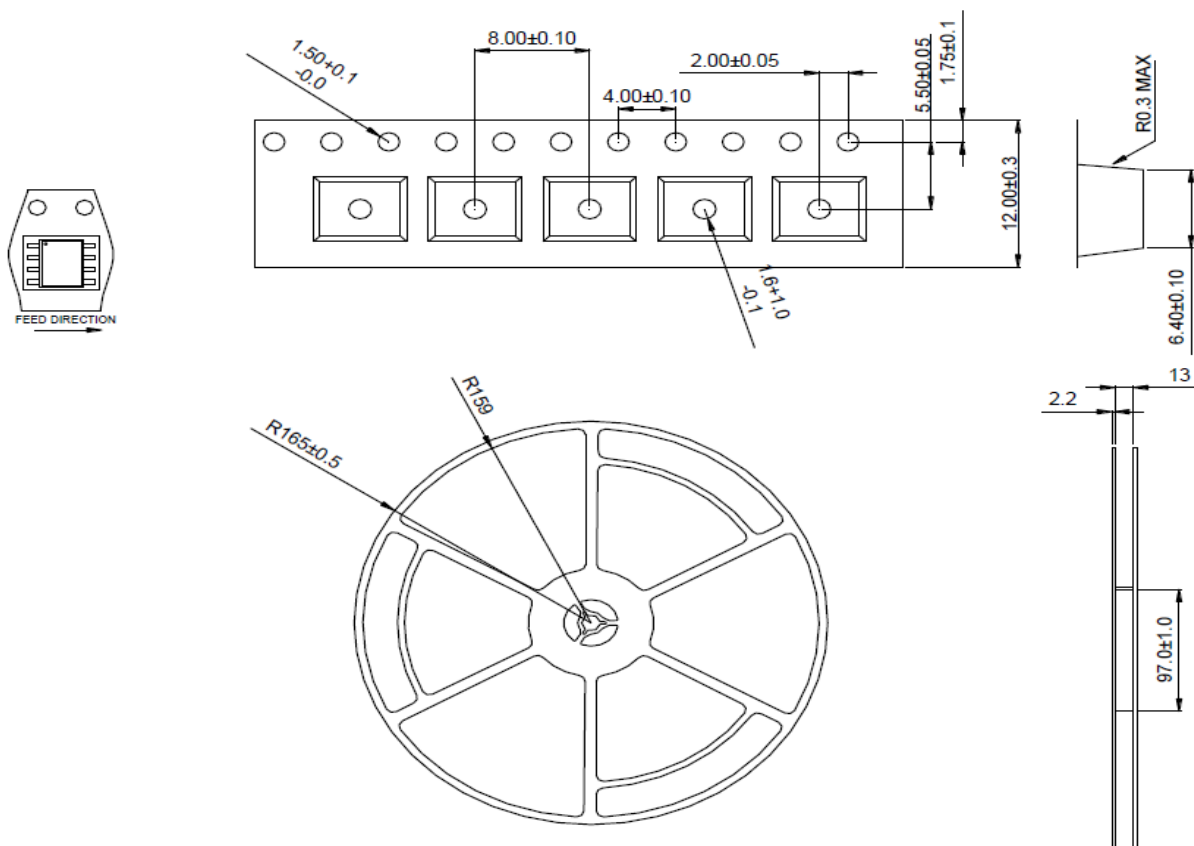
# PV563BA

## P-Channel Enhancement Mode MOSFET

### A. Marking Information



### B. Tape&Reel Information:2500pcs/Reel

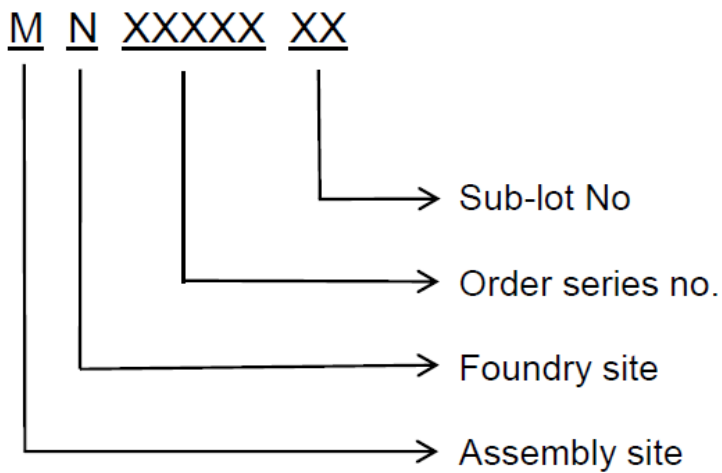


# PV563BA

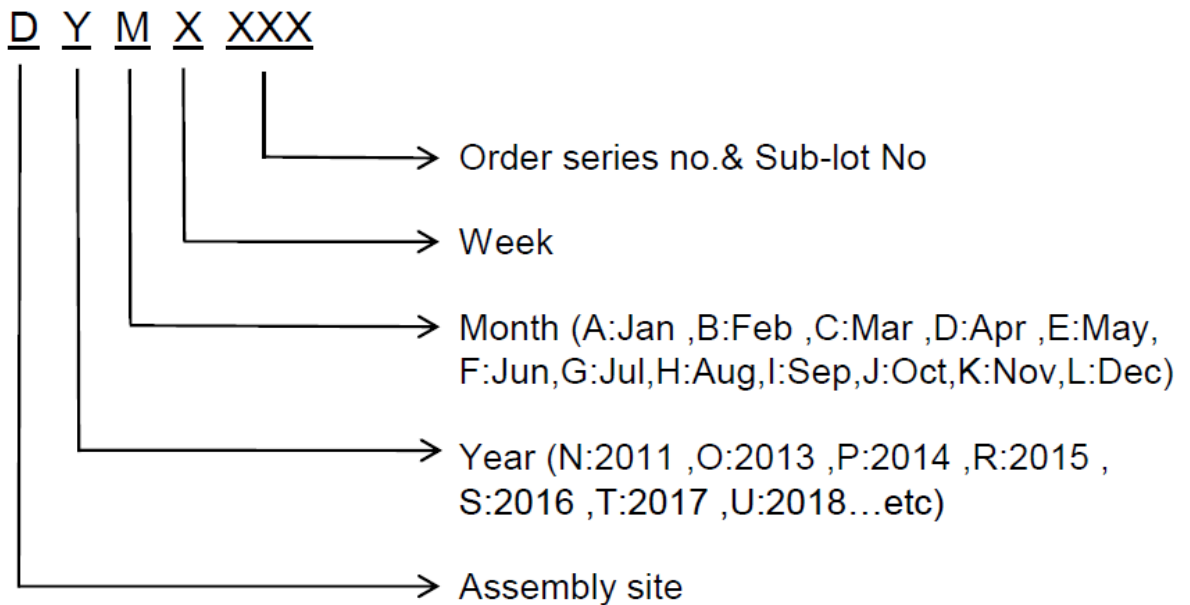
## P-Channel Enhancement Mode MOSFET

### C. Lot No.&Date Code rule

#### 1.Lot No.



#### 2.Date Code





**PV563BA**  
**P-Channel Enhancement Mode MOSFET**

**D.Label rule**

标签内容(Label content)



1	Label Size	30 * 90 mm
2	Font style	Times New Roman or Arial (或可区分英文"0"和数字"0", "G"和"Q"的字型即可)
3	U-NIKC	Height: 4 mm
4	Package	Height: 2 mm
5	Date	Height: 2 mm Shipping date: YYYY/MM/DD, ex. 2008/09/12
6	Device	Height: 3 mm (Max: 16 Digit)
7	Lot	Height: 3 mm (Max: 9 Digit) Sub lot
8	D/C	Height: 3 mm (Max: 7 Digit)
9	QTY	Height: 3 mm (Max: 6 Digit) Thousand mark is no needed
10	RoHS label	 long axis: 12 mm minor axis: 6 mm bottom color: White Font color: Black Font style: Arial
11	Halogen Free label	 Diameter: 10 mm bottom color: Green Font color: Black Font style: Arial
12	Scan information	Device / Lot / D/C / QTY , Insert " / " between every parts. for example: P3055LDG/G12345601/GGG2301/2000 DPI (Dots per inch): Over 300 dpi Code : Code 128 Height: 6 mm at least